

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	324	438/118,464,119,107,109,110,112,124,126,127,612,618,617,666.ccls. and tape and (chip or die) and ball and stack	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 08:43
L5	196	438/118,464,119,107,109,110,112,124,126,127,612,618,617,666.ccls. and tape and (chip or die) and ball and stack and @ad<="20021230"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:09
L6	7	"438"/\$.ccls. and ((roll\$4 or fold\$4) adj tape) and adhesive and (chip or die) and ball and stack and @ad<="20021230"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:10
L7	13	"257"/\$.ccls. and ((roll\$4 or fold\$4) adj tape) and adhesive and (chip or die) and ball and stack and @ad<="20021230"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:13
L8	11	semiconductor and ((roll\$4 or fold\$4) adj tape) and adhesive and (chip or die) and ball and stack and @ad<="20021230"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:16
L9	0	(semiconductor and ((roll\$4 or fold\$4) adj tape) and adhesive and (chip or die) and ball and stack).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:16
L10	0	(semiconductor and ((roll\$4 or fold\$4) adj tape) and adhesive and (chip or die) and ball and stack).clm.	US-PGPUB	OR	ON	2005/12/14 09:16
L11	1240	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:24
L12	1497	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:29

L13	366	(438/119).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:29
L14	844	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:33
L15	34	438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:34
L16	6	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	USPAT	OR	ON	2005/12/14 09:34
S1	1	("20040180471").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/21 14:40
S2	993	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:17
S3	598	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 09:33
S4	469	(438/112).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41

S5	767	(438/124).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S6	750	(438/126).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S7	1104	(438/127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S8	973	(438/618).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S9	556	(438/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S10	321	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:42
S11	342	(438/110).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:30
S12	13	semiconductor same stack\$5 same lead same (flux or reflow or encapsul\$6) same solder same ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 09:59
S13	2	semiconductor with stack\$5 with lead with (flux or reflow or encapsul\$6) with solder with ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 08:15

S16	2528	semiconductor and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 11:47
S17	343	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 08:39
S18	422	257/685,686,784,786,773,777,723.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 12:57
S19	1	("20040157374").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 12:55
S20	2	("6656840").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/27 09:48
S22	47	(anisotropic adj conduct\$5 adj adhesive) same (chip or die or ((integrated adj circuit) or ("IC"))) same (solder adj ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 06:42
S23	5	(anisotropic adj conduct\$5 adj adhesive) with fold\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 06:44
S24	14	(anisotropic adj conduct\$5 adj adhesive) same fold\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:48
S26	1	("6790710").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 10:10

S30	5	((("5523605") or ("20040152290") or ("6683350"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:37
S36	2	((("6836006") or ("20020043708"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/28 14:17
S38	7	(anisotropic adj conduct\$5 adj adhesive) with (semiconductor adj packag\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:49
S39	1068	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/23 10:50
S40	71	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and (anisotropic adj conduct\$5 adj adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:52
S42	5	((("6300679") or ("6737300") or ("6635968") or ("6620652") or ("6582992"))).PN.	USPAT	OR	OFF	2004/12/27 09:48
S43	2	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07
S44	6	"438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:05
S45	93	"438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
S46	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06

S47	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
S48	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
S49	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07
S50	93	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:09
S51	199	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07
S52	30	438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 09:34
S53	2	438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:09
S54	8	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:21
S55	15	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:21

S56	11	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	USPAT	OR	ON	2005/05/31 12:21
S57	6	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	USPAT	OR	ON	2005/12/14 09:34
S58	1	("6765288").PN.	USPAT	OR	OFF	2005/11/28 14:17